

AM42-0007-DIE

GaAs MMIC Power Amplifier, 2 W
14.0 - 14.5 GHz

Rev. V5

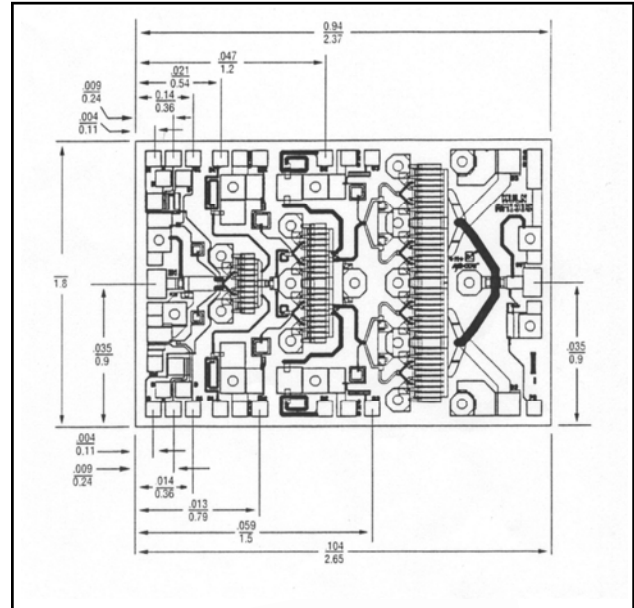
Features

- High Linear Gain: 22 dB Typical.
- High Saturated Output Power: +33 dBm Typical
- High Power Added Efficiency: 22% Typical
- High P1dB: +32 dBm Typical
- 50 Ω Input / Output Broadband Matched
- Integrated Output Power Detector
- High Performance Ceramic Bolt Down Package

Description

M/A-COM's AM42-0007-DIE is a three stage MMIC linear power amplifier fabricated on a mature 0.5 micron MBE based GaAs process. The AM42-0007-DIE employs a fully matched chip with integral bias networks and output power detector. This GaAs MMIC power amplifier is ideally suited for used as an output stage or driver in applications for VSAT applications.

Functional Schematic



Ordering Information

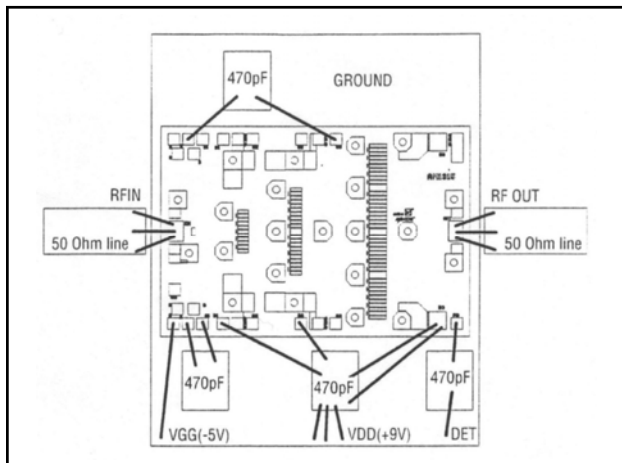
| Part Number | Package |
|---------------|---------|
| AM42-0007-DIE | DIE |

Absolute Maximum Ratings^{1,2}

| Parameter | Absolute Maximum |
|---------------------|-------------------|
| V_{DD} | +12 Volts |
| V_{GG} | -10 Volts |
| Power Dissipation | 17.9 W |
| RF Input Power | +23 dBm |
| Channel Temperature | +150 °C |
| Storage Temperature | -65 °C to +150 °C |

1. Exceeding any one or combination of these limits may cause permanent damage to this device.
2. Back of die temperature (T_B) = +25°C.

Typical Bias Configuration ^{3,4}



3. Nominal bias is obtained by first connecting -5 volts to pin V_{GG} (resistor network used) followed by connecting $+9$ volts to pin V_{DD} . Note sequence.
4. It is recommended that the die be mounted with Au/Sn eutectic performs for good RF ground and thermal interface.

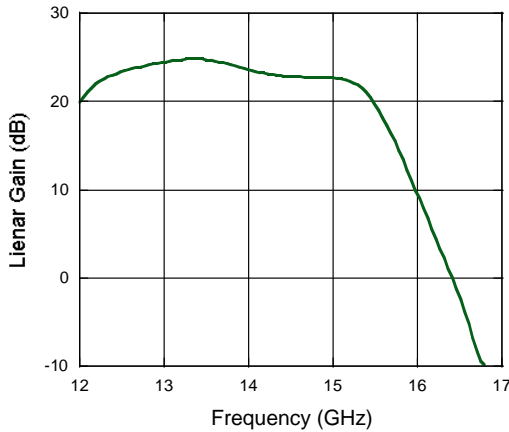
Electrical Specifications ⁵: $T_B = +25^\circ\text{C}$, $V_{DD} = +9\text{ V}$, $V_{GG} = -1.2\text{ V}$, $Z_0 = 50\ \Omega$

| Parameter | Test Conditions | Units | Min. | Typ. | Max. |
|---------------------------------------|---|--------------------|------|-------|------|
| Linear Gain | $P_{IN} < 0\text{ dBm}$ | dB | — | 22 | — |
| Input VSWR | — | Ratio | — | 2.5:1 | — |
| Output VSWR | — | Ratio | — | 2.7:1 | — |
| Saturated Output Power | $P_{IN} < +14\text{ dBm}$ | dBm | — | +33 | — |
| Output Power @ 1 dB Compression | — | dBm | 31 | +32 | — |
| Output IP_3 | — | dBm | — | 41 | — |
| Power Added Efficiency (PAE) | $P_{IN} < +14\text{ dBm}$ | % | — | 22 | — |
| Bias Current | I_{DSQ} (No RF) | mA | — | 850 | — |
| | I_{GG} (No RF) | mA | — | 0.1 | — |
| Thermal Resistance | θ_{CB2} ⁶ | $^\circ\text{C/W}$ | — | 7 | — |
| Detector Output Voltage (V_{DET}) | Pin = +3 dBm, $I_{ds} = 750\text{ mA}$ Typ. | V | — | +3.5 | — |

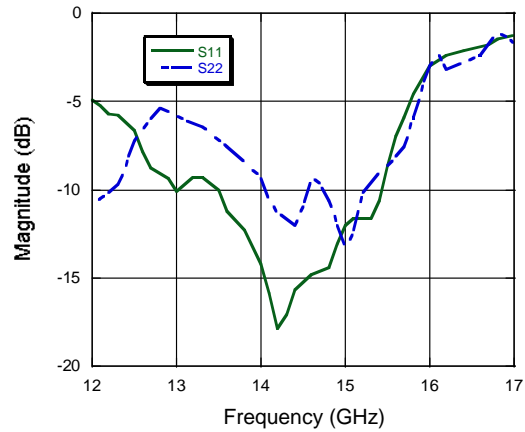
5. 100% on wafer tested (50 μs pulse width, 20% duty factor) without resistor network on gates.
6. Channel to die backside.

Typical Performance @ 25°C

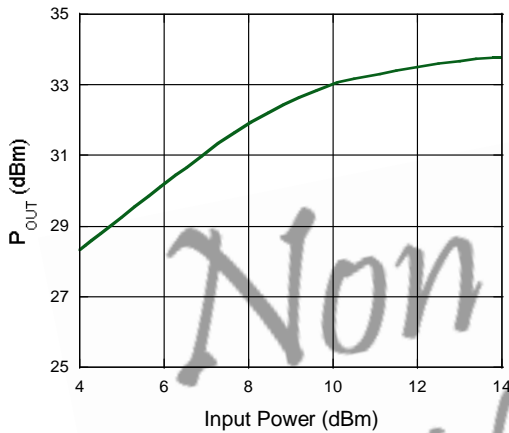
Linear Gain vs. Frequency



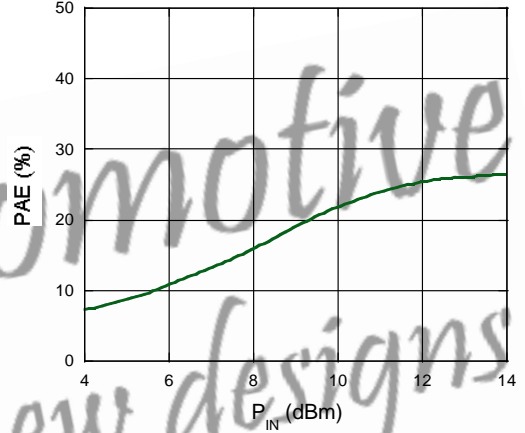
Input & Output Return Loss vs. Frequency



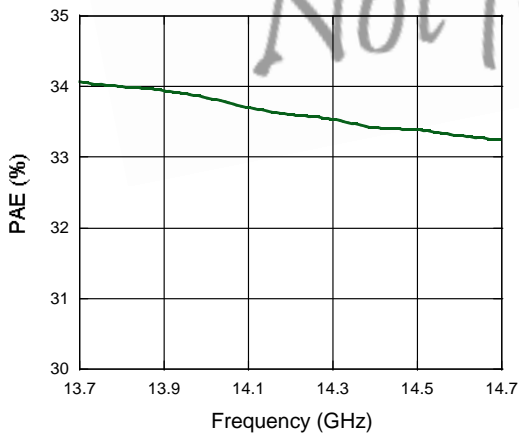
Output Power vs. Input Power @ 14 GHz



Power Added Efficiency vs. Input Power @ 14 GHz



Output Power vs. Frequency @ $P_{IN} = +14$ dBm



PAE vs. Frequency @ $P_{IN} = +14$ dBm

